



FF1923 - Sn/Pb SOLDER BALLS
FFG1923 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	3.20	\approx	3.85	3
A ₁	0.40	0.50	0.60	
A ₂	1.10	\approx	1.50	
$\frac{D}{E}$	45.00 BASIC			
$\frac{D_1}{E_1}$	43.00 REF			
$\frac{e}{e}$	1.00 BASIC			
ϕ_b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
bbb	\approx	\approx	0.25	
ddd	\approx	\approx	0.25	
eee	\approx	\approx	0.10	
M	44			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. ACTUAL SOLDER BALL COUNT = 1924

PK395_01_100709

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/20/09	1.0	Initial Xilinx release.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.